

1. 2018 년 교육 계획

분기	차수	일시	내용	정원
1/4	39 차	2018.01.18	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	40 차	2018.02.22	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	74 차	2018.03.15	<u>MultiPrep System Users Meeting:</u> Cross-Section/ TEM Wedge Sample Preparation	6 명
2/4	41 차	2018.04.12	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	42 차	2018.05.17	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	75 차	2018.06.21	<u>MultiPrep System Users Meeting:</u> Parallel Thinning for Die & Package Analysis	6 명
3/4	43 차	2018.07.12	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	44 차	2018.08.23	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	76 차	2018.09.13	<u>MultiPrep System Users Meeting:</u> Cross-Section/ TEM Wedge Sample Preparation	6 명
4/4	45 차	2018.10.18	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	46 차	2018.11.15	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	77 차	2018.12.13	<u>MultiPrep System Users Meeting:</u> Parallel Thinning for Die & Package Analysis	6 명

2. 교육상세내역

MultiPrep System

- 교육대상: MultiPrep System
- 교육참가비용: 10 만원/1 인 (단, 장비보유고객 1 인/1 회 무상)
- 교육참가인원: 선착순 6 명
- 강사: 센터 책임 및 담당연구원

1. Cross-Section/TEM Wedge Sample Preparation

10:00AM~10:50AM	MultiPrep system application
11:00AM~11:50AM	Equipment Calibration 교육 및 실습
12:00PM~01:00PM	점심식사
01:15PM~02:40PM	Sample제작1(Cross-section)
03:00PM~06:00PM	Sample제작2(Wedge Cross-section)

2. Parallel Thinning for Microelectronic device / SIMS sample preparation

10:00AM~10:50AM	MultiPrep system application
11:00AM~11:50AM	Equipment Calibration 교육 및 실습
12:00PM~01:00PM	점심식사
01:00PM~02:10PM	Sample제작1(Parallel Thinning / Sample preparation)
02:30PM~04:00PM	Sample제작2(Back-side Thinning / Thinning 실습)

Basic Course

- 교육대상: 미세조직 관찰법을 배우려는 초보자(금속분야, 전자재료분야)
- 교육참가비용: 5 만원/1 인
- 교육참가인원: 선착순 10 명
- 강사: 센터 책임 및 담당연구원

1. Microstructures Sample preparation for Electronic Materials

10:00AM~11:00AM	시편준비방법 및 관찰법
11:10AM~11:50AM	Sectioning 장비 작동법 및 실습
12:00PM~01:00PM	점심식사
01:15PM~02:15PM	Cold Mounting 실습
02:30PM~03:30PM	Polishing 실습 1
03:50PM~05:00PM	Polishing 실습 2

2. Microstructures Sample preparation for Metallurgy

10:00AM~11:00AM	시편준비방법 및 관찰법
11:10AM~11:50AM	Sectioning 장비 작동법 및 실습
12:00PM~01:00PM	점심식사
01:15PM~02:15PM	Hot Mounting/Cold Mounting 실습
02:30PM~03:30PM	Polishing 및 관찰 실습 1
03:50PM~04:40PM	Polishing 및 관찰 실습 2